

3.2x2.4mm SMD CHIP LED LAMP

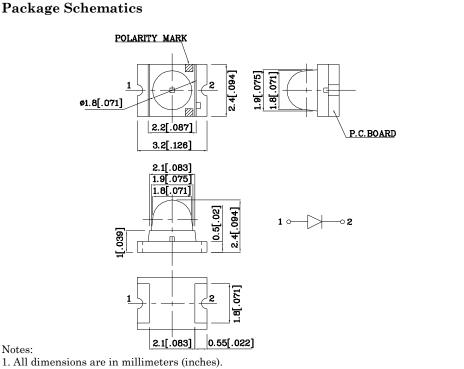
## **Features**

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 1,500pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



2. Tolerance is  $\pm 0.1(0.004")$  unless otherwise noted.

Notes:

3. Specifications are subject to change without notice.

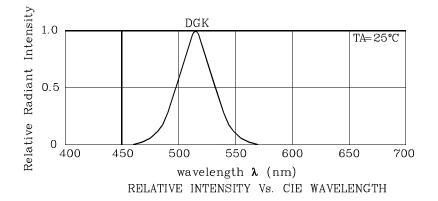
Absolute Maximum Ratings (T <sub>A</sub> =25°C)	DGK (InGaN)	Unit		
Reverse Voltage V <sub>R</sub>		5	V	
Forward Current	$\mathbf{I}_{\mathrm{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	$\mathbf{P}_{\mathrm{D}}$	102.5	mW	
Electrostatic Discharge Threshold (HBM)	450	V		
Operating Temperature T <sub>A</sub>		$-40 \sim +85$	°C	
Storage Temperature	Tstg	-40 ~ +85		

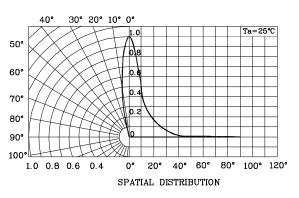
Operating Characteristics (T <sub>A</sub> =25°C)	DGK (InGaN)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\rm F}$	3.3	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\rm F}$	4.1	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	50	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λP	515*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λD	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$ riangle\lambda$	35	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	45	pF

min. typ.   ZDGK78W Green InGaN Water Clear 1900* 2890* 515* 20	Part Number	Emitting Color	Emitting Material	Lens-color	CIE12'	s Intensity 7-2007* nA) mcd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
ZDGK78W Green InGaN Water Clear 1900* 2890* 515* 20					min.	typ.		
	ZDGK78W	Green	InGaN	Water Clear	1900*	2890*	515*	20°

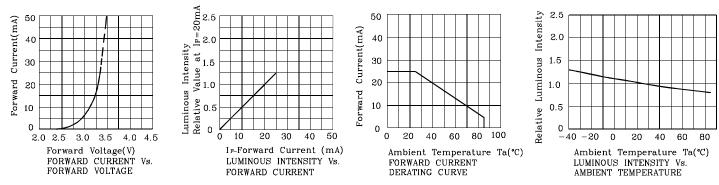
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



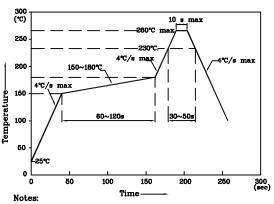




✤ DGK



## LED is recommended for reflow soldering and soldering profile is shown below.



Reflow Soldering Profile for SMD Products (Pb-Free Components)

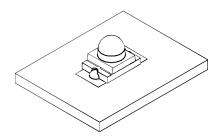
1. Maximum soldering temperature should not exceed 260°C 2. Recommended reflow temperature: 145°C-260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

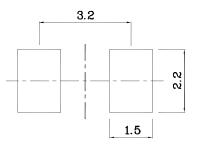
high temperatures conditions



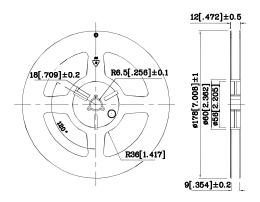
The device has a single mounting surface. The device must be mounted according to the specifications.



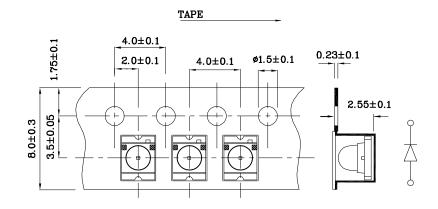
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



## Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

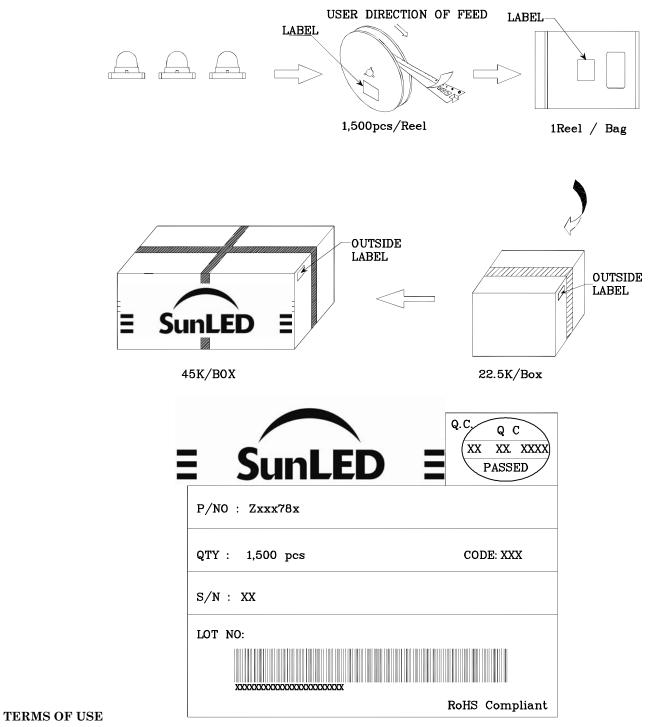
3. Forward Voltage: +/-0.1V  $\,$ 

Note: Accuracy may depend on the sorting parameters.

Feb 18,2014



## PACKING & LABEL SPECIFICATIONS



- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{http://www.SunLED.com/TechnicalNotes}$